

Amendments to the Claims

This listing of the Claims will replace all prior versions and listings of the claims in this patent application.

Listing of the Claims

Claims 1-25 (canceled)

26. (previously presented) A method for checking an electronic package, comprising:

providing said electronic package with a mark; and

reading said mark using a laser code reader.

27. (previously presented) The method of claim 26, wherein said mark comprises a bar code.

28. (previously presented) The method of claim 26, wherein said mark comprises an identity for a product.

29. (previously presented) The method of claim 26, wherein said mark comprises an identity for a manufacturer.

30. (previously presented) The method of claim 26, wherein said electronic package comprises a semiconductor chip and a protecting structure, said semiconductor chip having a

surface with said mark, said protecting structure being over said mark, wherein said mark is visible through said protecting structure.

31. (previously presented) The method of claim 30, wherein said surface further comprises multiple pads.

32. (previously presented) The method of claim 30, wherein said semiconductor chip has another surface with multiple pads.

33. (currently amended) An electronic package comprising a ~~laser-readable mark~~ read by a laser code reader.

34. (currently amended) The electronic package of claim 33, wherein said ~~laser-readable~~ mark comprises a bar code.

35. (currently amended) The electronic package of claim 33, wherein said ~~laser-readable~~ mark comprises an identity for a product.

36. (currently amended) The electronic package of claim 33, wherein said ~~laser-readable~~ mark comprises an identity for a manufacturer.

37. (currently amended) The electronic package of claim 33 comprising a semiconductor chip and a protecting structure, said semiconductor chip having a surface with said ~~laser~~

~~readable~~ mark, said protecting structure being over said ~~laser readable~~ mark, wherein said mark is visible through said protecting structure.

38. (currently amended) A semiconductor chip having a surface with a ~~laser readable~~ mark read by a laser code reader.

39. (currently amended) The semiconductor chip of claim 38, wherein said ~~laser readable~~ mark comprises a bar code.

40. (currently amended) The semiconductor chip of claim 38, wherein said ~~laser readable~~ mark comprises an identity for a product.

41. (currently amended) The semiconductor chip of claim 38, wherein said ~~laser readable~~ mark comprises an identity for a manufacturer.

42. (previously presented) The semiconductor chip of claim 38, wherein said surface further comprises multiple pads.

43. (previously presented) The semiconductor chip of claim 38, wherein said semiconductor chip has another surface with multiple pads.

44. (previously presented) An electronic package comprising:

a semiconductor chip having a first surface with multiple pads and a second surface with a mark; and

a protecting structure over said mark, wherein said mark is visible through said protecting structure.

45. (currently amended) The electronic package of claim 44, wherein said mark comprises a bar code.

46. (previously presented) The electronic package of claim 44, wherein said mark comprises a number.

47. (previously presented) The electronic package of claim 44, wherein said mark comprises an identity for a product.

48. (previously presented) The electronic package of claim 44, wherein said mark comprises an identity for a manufacturer.

49. (previously presented) The electronic package of claim 44, wherein said mark is colored.

50. (previously presented) An electronic package comprising:

a semiconductor chip having a surface with a mark comprising a number, a bar code, or an identity for a product or a manufacturer; and

a protecting structure over said mark, wherein said mark is visible through said protecting structure.

51. (previously presented) The semiconductor chip of claim 50, wherein said surface further comprises multiple pads.

52. (previously presented) The semiconductor chip of claim 50, wherein said semiconductor chip has another surface with multiple pads.